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EET U.S. DEPARTMENT OF COMMERCE Patent and Trademark Office 101604265 To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof. Name and address of receiving party(ies): Name of conveying party(ies): いいいい Taiwan Semiconductor Manufacturing Co. Ltdv Tien-I Bao Lian-Jong Li No. 121 Park Avenue III Cheng Chung Lin Science-Based Industrial Park Syun-Ming Jang Hsin-Chu, Taiwan, R.O.C. Nature of conveyance: Additional name(s) & address(es) attached □ Yes ⋈ No Assignment Merger ☐ Security Agreement Change of Name Other: Execution Date: August 1, 2000 Application number(s) or patent number(s): If this document is being filed together with a new application, the execution date of the application is: __08-01-00_ B. Patent No(s) A. Patent Application No(s). 09761 477 Additional numbers attached? □ Yes ⊠ No Total number of applications and patents involved: Name and address of party to whom correspondence concerning document should be mailed: \$40.00 Total fee (37 CFR 3.41) RANDY W. TUNG **Tung & Associates** 838 W. Long Lake Road **Enclosed** Suite 120 Bloomfield Hills, Michigan 48302 Authorized to be charged to deposit account 50-0484 Deposit Account Number: 1/22/4001 MWDLDER1 00000096 09761422 (Attach duplicate copy of this page if paying by deposit 40.00 DP op FC:581 DO NOT USE THIS SPACE 9 Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. Randy W. Tung Signature Name of Person Signing Registration No. 31,311 Total number of pages including cover sheet, attachments, and document $\underline{}$

Mail documents to be recorded with required cover sheet information to: Commissioner of Patents & Trademarks, Box Assignments Washington, D.C. 20231

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PATENT REEL: 011479 FRAME: 0120

ASSIGNMENT

WHEREAS, we, <u>LAIN-JONG LI, TIEN-I BAO, CHENG CHUNG LIN</u> and <u>SYUN-MING JANG</u> have invented certain improvements in SOFT PLASMA OXIDIZING PLASMA METHOD FOR FORMING ADHERENT CARBON DOPED SILICON CONTAINING DIELECTRIC LAYER for which we are about to make application for Letters Patent of the United States; and

WHEREAS, TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD. of No. 121, Park Avenue 3, Science-Based Industrial Park, Hsin-Chu, Taiwan, R.O.C, is desirous of acquiring the entire right, title and interest in and to said invention;

NOW, THEREFORE, in consideration of One Dollar (\$1.00) and other good and valuable consideration, the receipt of which is hereby acknowledged, we, LAIN-JONG LI, TIEN-I BAO, CHENG CHUNG LIN and SYUN-MING JANG, by these presents, do hereby sell, assign and transfer unto the said corporation and its assigns, for the territory of the United States of America and all foreign countries, the entire right, title and interest, including all priority rights under the International Convention associated with each country of the Union, in and to said invention as described in the patent application executed by us on the ___1st__ day of ___August___, 2000, preparatory to obtaining Letters Patent of the United States thereon, and in and to said application and any Letters Patent that may be granted in pursuance of said application and any divisional,

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PATENT REEL: 011479 FRAME: 0121 continuation or continuation-in-part application thereof, and in and to any reissue of any such patent. and in and to any patent applications which may be filed on said invention in countries foreign to the United States and any Letters Patent granted thereon.

We further authorize said corporation to apply for foreign patents on said invention in its own name or through its designees, including subsidiaries, related companies or assignees, under the International Convention or otherwise, and we further agree to execute all papers, including those required for the United States and foreign applications, and to perform such other proper acts as said corporation or its designees the rights herein assigned.

Lain-Jong Li

Cheng-Chung Lin SYUN-MING JANG

TUNG & ASSOCIATES 838 W. Long Lake Road Suite 120 Bloomfield Hills, Michigan 48302

RECORDED: 01/16/2001

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PATENT REEL: 011479 FRAME: 0122